

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L6	3	("5024732").URPN.	USPAT	OR	ON	2008/04/30 10:58
L7	8	"1160846"	EPO; DERWENT	OR	ON	2008/04/30 11:18
S1	2	"5292424".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/28 12:30
S2	2	"4776939".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/28 12:31
S3	2	"4959137".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/28 12:32
S4	58	("204" "205").clas. and circuit adj board and line with convey\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/28 14:15
S5	20	"3236545"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/28 14:21
S6	14	hubel\$-e\$.in. and (("204" "205").clas. c25 \$7.ipc.)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/28 14:41
S7	143228	((("204" "205").clas c25 \$7.ipc.)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/28 14:52
S8	3818	S7 and adjacent with (substrate workpiece board)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/28 14:52

S9	49	S7 and adjacent with (substrate workpiece board) same resistor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/28 14:53
S10	434	S7 and adjacent with (substrate workpiece board) same etch\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/28 15:01
S11	4	S7 and adjacent with (substrate workpiece board) same (voltage potential) with difference with (prevent \$4 minimiz\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/28 15:02
S12	3355	S8 and (electroplat\$ plating deposit\$3 electrodeposit\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/28 15:06
S13	65046	S7 and (electroplat\$ plating deposit\$3 electrodeposit\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/28 15:06
S14	1615	S13 and (adjacent neighbor\$3) near2 (substrate workpiece (circuit adj board))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/28 15:06
S15	240	S13 and (adjacent neighbor\$3) near2 (substrate workpiece (circuit adj board)) same (voltage potential)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/28 15:07
S16	176978	(sputtering plasma glucose magnetron).ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/28 15:21
S17	190	S15 not S16	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/28 15:21
S18	40	"619846"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/28 15:28

S19	483	204/202-205.ccls. 204/230.7.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/28 15:40
S20	27	S19 and (adjacent neighbor\$5) with (circuit adj board substrate workpiece)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/28 15:41
S21	10	("5292424").URPN.	USPAT	OR	ON	2008/04/28 15:48
S22	11	S7 and potential with immersion with lower	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/28 16:03
S23	2	S7 and potential with immersion with etch\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/28 16:05
S24	7	"2951708"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/28 16:10
S25	46	"308636"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/28 16:12
S26	2	"5024732".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/28 16:13
S27	4	"0129290"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/28 16:22
S28	79	("204" "205").clas and (semiconductor wafer electronic microelectronic microfeature) and immers\$4 same (bias \$3 potential) same (protect\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/29 10:17

S29	173	("204" "205").clas. and (semiconductor wafer electronic microelectronic microfeature) and immers\$4 same (bias\$3 potential) same (etch\$3)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/29 10:19
S30	714	("204" "205").clas. and (semiconductor wafer electronic microelectronic microfeature) and immers\$4 with (bias\$3 potential)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/29 10:20
S31	65	("204" "205").clas. and (semiconductor wafer electronic microelectronic microfeature) and immers\$4 with (bias\$3 potential voltage) same (etch\$3 protect \$3 damag\$3) same (plating electroplat\$ electrodeposit\$3 deposit\$3)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/29 10:21
S32	111	("20010015321" "2742413" "2882209" "3627661" "3649509" "3727620" "3770598" "4027686" "4065374" "4092176" "4110176" "4113492" "4120759" "4129480" "4315059" "4326940" "4336114" "4376685" "4396467" "4405416" "4428815" "4435266" "4489740" "4496436" "4510176" "4518678" "4519846" "4693805" "4732785" "4789445" "4869971" "4891106" "4898647" "5039381" "5055425" "5092975" "5155336" "5162260" "5178813" "5222310"	US-PGRUB; USPAT; USOCR	OR	ON	2008/04/29 10:48

		"5224504" "5230743" "5252807" "5256274" "5259407" "5290361" "5302256" "5316974" "5328589" "5349978" "5368711" "5377708" "5384640" "5415890" "5429733" "5447615" "5454930" "5516412" "5516414" "5528118" "5608943" "5625170" "5651865" "5670034" "5705223" "5723028" "5730890" "5838121" "5885469" "6024856" "6071388" "6074544" "6093291" "6113771" "6133061" "6162344" "6174425" "6197181" "6203582" "6203684" "6210555" "6224737" "6251236" "6254760" "6258220" "6261433" "6261733" "6267853" "6277263" "6290833" "6303014" "6319384" "6340633" "6344419" "6350366" "6391166" "6395101" "6399479" "6409903" "6423636" "6432821" "6432832" "6440291" "6551484" "6551488" "6565729" "6632345" "6638410").PN.				
S33	8	("204" "205").clas. and loading adj bias with immers\$4	US-PGRUB; USPAT; USOCR	OR	ON	2008/04/29 12:39
S34	3	"1160846"	US-PGRUB; USPAT; USOCR	OR	ON	2008/04/29 12:41
S35	11	"1160846"	US-PGRUB; USPAT; USOCR; EPO; DERWENT	OR	ON	2008/04/29 12:41

S36	2	"6913680".pn.	US-PGPUB; USPAT; USOCR; EPO; DERWENT	OR	ON	2008/04/29 12:44
S37	7	("4129480" "4120759").pn.	US-PGPUB; USPAT; USOCR; EPO; DERWENT	OR	ON	2008/04/29 12:45

4/30/08 11:23:29 AM

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